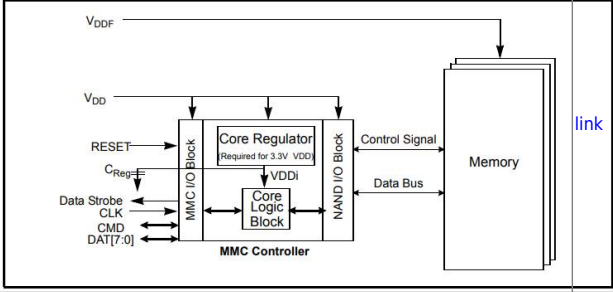
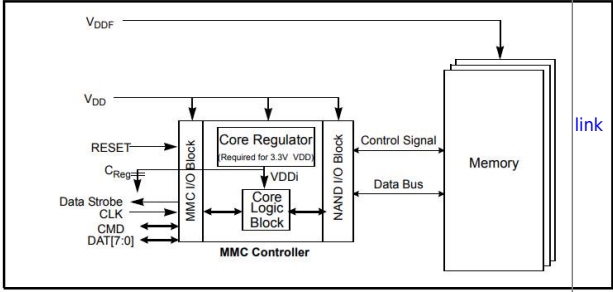
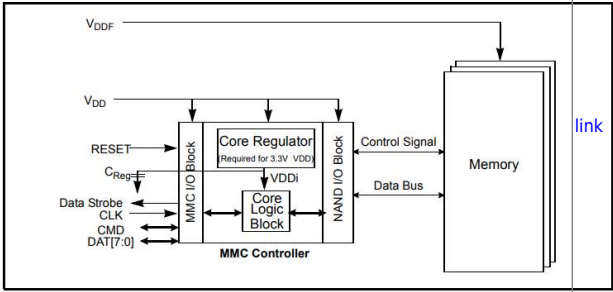
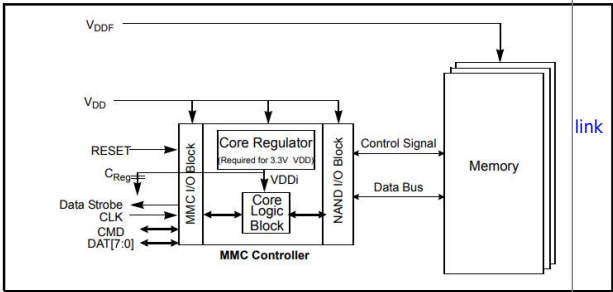
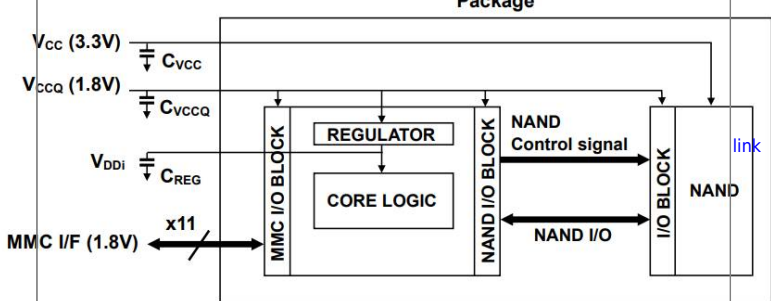


Содержание

eMMC	3
Manufacturers	3

eMMC

Manufacturers

P\N	MFG	Dens	CASE	Interface	Memory Struct	Link
KLM8G1GETF-B041	SAMSUNG	8GB	153FBGA	VDD (1.70V ~ 1.95V or 2.7V ~ 3.6V)	VDE (2.7 ~ 3.6V) - eMMC consists of NAND Flash and Controller. V _{DD} (V _{CCQ}) is for Controller power and V _{DDF} (V _{CC}) is for flash power	 link
KLMAG1JETD-B041	SAMSUNG	16GB	153FBGA	VDD (1.70V ~ 1.95V or 2.7V ~ 3.6V)	VDE (2.7 ~ 3.6V) - eMMC consists of NAND Flash and Controller. V _{DD} (V _{CCQ}) is for Controller power and V _{DDF} (V _{CC}) is for flash power	 link
KLMBG2JETD-B041	SAMSUNG	32GB	153FBGA	VDD (1.70V ~ 1.95V or 2.7V ~ 3.6V)	VDE (2.7 ~ 3.6V) - eMMC consists of NAND Flash and Controller. V _{DD} (V _{CCQ}) is for Controller power and V _{DDF} (V _{CC}) is for flash power	 link
KLMCG4JETD-B041	SAMSUNG	64GB	153FBGA	VDD (1.70V ~ 1.95V or 2.7V ~ 3.6V)	VDE (2.7 ~ 3.6V) - eMMC consists of NAND Flash and Controller. V _{DD} (V _{CCQ}) is for Controller power and V _{DDF} (V _{CC}) is for flash power	 link
THGAMRG7T13BAIL	KIOXIA	16GB	153FBGA	VCCQ = 1.7V to 1.95V VCC (2.7 ~ 3.6V) VDDi MMC I/F (1.8V) x11	 link	

P\N	MFG	Dens	CASE	Interface	Memory	Struct	Link
THGBMNG5D1LBAIL	KIOXIA	4GB	153FBGA	VCCQ = 1.7V to 1.95V / 2.7V to 3.6V	VCC 2.7V / 3.6V		link